



APPENDIX

Changes to Abstract:

The following is a marked-up version of the amended Abstract.

ABSTRACT

In a flexible printed wiring board ~~10~~ obtained by connecting metal bumps ~~1a~~ of a first flexible printed wiring part ~~1~~ and connection pads ~~2a~~ of a second flexible printed wiring part ~~2~~, the first flexible printed wiring part ~~1~~ is composed of a conductive layer ~~4~~ and insulating layer ~~5~~ adjacent thereto, holes A being provided in the insulating layer ~~5~~ so as to reach the conductive layer ~~4~~, metal plugs ~~6~~ being formed in these holes A by an electrolytic plating method, metal bumps ~~1a~~ being produced by making the tips of these metal plugs ~~6~~ project from the insulating layer ~~5~~. In this way, as many as possible flexible printed wiring boards can be obtained from a laminated sheet for flexible printed wiring of prescribed size.